

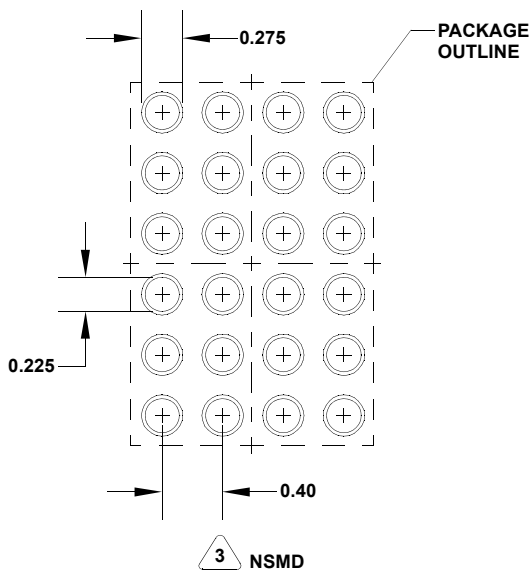
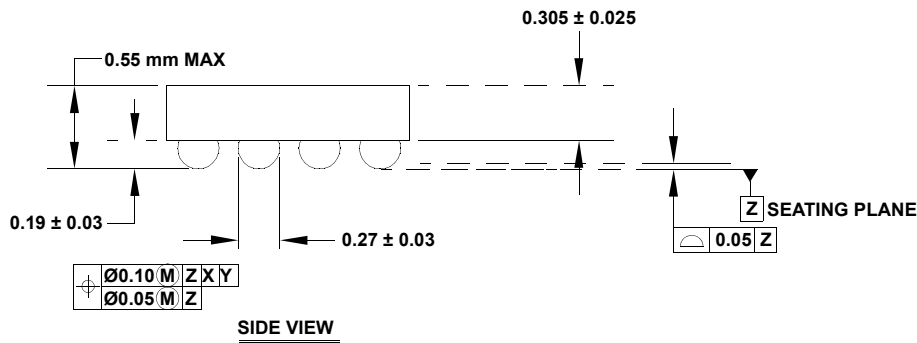
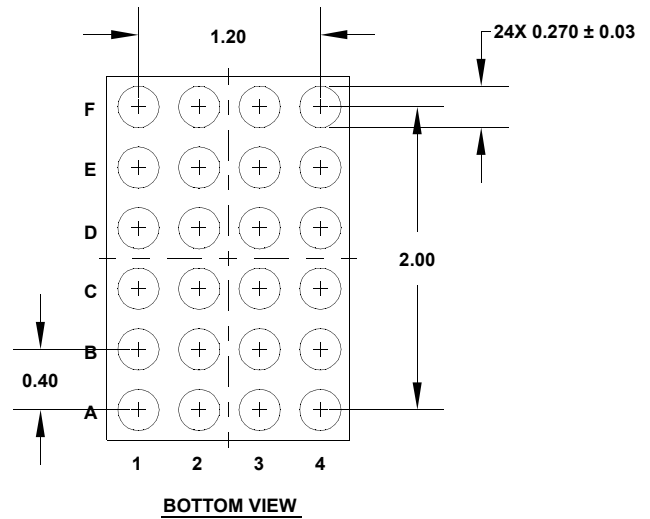
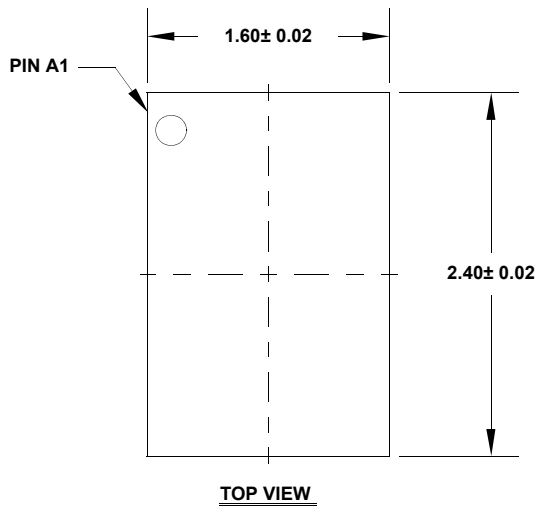
Plastic Packages for Integrated Circuits

Package Outline Drawing

W4x6.24

4x6 ARRAY 24 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP)

Rev 1, 9/10



NOTES:

1. All dimensions are in millimeters.
2. Dimension and tolerance per ASMEY 14.5M-1994, and JESD 95-1 SPP-010.
3. NSMD refers to Non-solder Mask Defined pad design per Intersil Tech Brief TB451 located at: <http://www.intersil.com/data/tb/tb451.pdf>.